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DOCKET NO.: H0498.70114US01/TJO

IN THE LEGITED STATES PATENT AND TRADEMARK OFFICE

Applicants:

Enoch KIM et al.

Serial No:

10/677,103

Confirmation. No.:

4302

Filed:

October 1, 2003

For:

MOLDED WAVEGUIDES

Examiner:

Not Yet Assigned

Art Unit:

1732

CERTIFICATE OF MAILING UNDER 37 C.F.R. §1.8(a)

The undersigned hereby certifies that this document is being placed in the United States mail with first-class postage attached, addressed to Commissioner for Patents, P.O. Box 1450, Alexandria, VA 22313-1450, on the day of June, 2004.

Garnine Wachesm Signature

Commissioner For Patents P.O. Box 1450 Alexandria, VA 22313-1450

Sir:

Transmitted herewith are the following documents:

[X] Information Disclosure Statement

[X] PTO Form 1449 with cited references

[X] Return Receipt Postcard

If the enclosed papers are considered incomplete, the Mail Room and/or the Application Branch is respectfully requested to contact the undersigned at (617) 720-3500, Boston, Massachusetts.

A check is not enclosed. If a fee is required, the Commissioner is hereby authorized to charge Deposit Account No. 23/2825. A duplicate of this sheet is enclosed.

Respectfully submitted, Enoch KIM et al., Applicant

Bv:

Timothy J. Oyer, Ph.D., Reg. No.: 36,628 WOLF, GREENWELD & SACKS, P.C.

600 Atlantic Avenue

Boston, Massachusetts 02210-2211

Telephone: (617)720-3500

Date: June ____, 2004

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JUN 0 4 2004 (5)

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THE UNITED STATES PATENT AND TRADEMARK OFFICE

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Signature Wachesan

Commissioner for Patents P.O. Box 1450 Alexandria, VA 22313-1450

STATEMENT FILED PURSUANT TO THE DUTY OF DISCLOSURE UNDER 37 CFR §§1.56, 1.97 AND 1.98

Sir:

Pursuant to the duty of disclosure under 37 C.F.R. §§1.56, 1.97 and 1.98, the Applicants request consideration of this Information Disclosure Statement.

PART I: Compliance with 37 C.F.R. §1.97

A. This Information Disclosure Statement has been filed before the mailing date of a first Office Action on the merits in the above-identified case. No fee or certification is required.

PART II: Information Cited

A. The Applicants hereby make of record in the above-identified application the information listed on the attached form PTO-1449 (modified). The order of presentation of the references should not be construed as an indication of the importance of the references.

Conf. No. 4302

PART III: Remarks

Documents cited anywhere in the Information Disclosure Statement are enclosed unless otherwise indicated. It is respectfully requested that:

- 1. The Examiner consider completely the cited information, along with any other information, in reaching a determination concerning the patentability of the present claims;
- 2. The enclosed form PTO-1449 be signed by the Examiner to evidence that the cited information has been fully considered by the Patent and Trademark Office during the examination of this application;
- 3. The citations for the information be printed on any patent which issues from this application.

By submitting this Information Disclosure Statement, the Applicants make no representation that a search has been performed, of the extent of any search performed, or that more relevant information does not exist.

By submitting this Information Disclosure Statement, the Applicants make no representation that the information cited in the Statement is, or is considered to be, material to patentability as defined in 37 C.F.R. §1.56(b).

By submitting this Information Disclosure Statement, the Applicants make no representation that the information cited in the Statement is, or is considered to be, in fact, prior art as defined by 35 U.S.C. §102.

Notwithstanding any statements by the Applicants, the Examiner is urged to form his own conclusion regarding the relevance of the cited information.

An early and favorable action is hereby requested.

Respectfully submitted, Enoch KIM et al., Applicants

Rv

Timothy J. Oyer Ph.D., Reg. No. 36,628

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Docket No. H0498.70114US01

Date: June \perp , 2004

XNDDX

JUN 0 4 2004 650

FORM PTO-1449(Modified)

ATTY. DOCKET NO. H0498.70114US01

SERIAL NO. 10/677,103

LIST OF PATENTS AND PUBLICATIONS FOR APPLICANT'S INFORMATION DISCLOSURE STATEMENT

APPLICANT Enoch Kim et al.

FILING DATE 10/01/2003

GROUP ART UNIT: 1732

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Exam Init	Ref Des	Document No.	Date	Name	Class	Sub Class	FILING DATE If Appropriate
	*	3,873,359	03/25/75	Lando			
	*	3,873,360	03/25/75	Lando	<u> </u>	<u> </u>	
	*	3,900,614	08/19/75	Lando			
	*	4,098,922	07/04/78	Dinella et al.	*		
	*	4,100,037	07/11/78	Baron et al.			
	*	4,192,764	07/11/80	Madsen			
	*	4,258,001	03/24/81	Pierce et al.			
	*	4,322,457	03/30/82	Baron et al.			
	*	4,472,458	09/18/84	Sirinyan et al.			
	*	4,508,755	04/02/85	Reintjes et al.			
×	*	4,555,414	11/26/85	Hoover et al.			
	*	4,637,904	01/87	Rounds			
	*	4,690,715	09/01/87	Allara et al.			
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	*	5,073,495	12/17/91	Anderson			
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	*	5,512,131	04/30/96	Kumar et al.			ļ
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	*	5,976,826	11/02/99	Singhvi et al.			

* a copy of this reference is not provided as it was previously cited by or submitted to the office in a prior application, Serial No. ______, filed _____, and relied upon for an earlier filing date under 35 U.S.C. 120 (continuation, continuation-in-part, and divisional applications).

Examiner	DATE CONSIDERED

EXAMINER: Initial if reference considered, whether or not citation is in conformance with MPEP 609; Draw line through citation if not in conformance and not considered.

FORM PTO-1449(Modified)

JUN 0 4 2004 0

ATTY. DOCKET NO. H0498.70114US01

SERIAL NO. 10/677,103

LIST OF PATENTS AND PUBLICATION FOR APPLICATION DISCLOSURE STATEMENT

APPLICANTS: Enoch Kim et al.

GROUP ART UNIT: 1732

U.S. PATENT DOCUMENTS

Exam Init	Ref Des	Document No.	Date	Name	Class	Sub Class	FILING DATE If Appropriate
	*	5,989,835	11/23/99	Dunlay et al.			
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* a c	opy of this reference is n	ot provided as it was	previously cited by	or submitted to th	e office in a prior	application, Seri	а
No.	, filed	, and relied upon for a	an earlier filing date	under 35 U.S.C.	120 (continuation,	, continuation-in-	
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Examiner DATE CONSIDERED

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